Title
2D material integration in 300 mm silicon production line

Abstract
We discuss the range of potential 2D material-based devices in current and future applications.
Many of today's 2D based devices are produced on a small-scale using lab based methods and frequently using lift-off processes. To allow 2D based products it is required to scale up the number of integrated devices as well as the wafer size. Moreover, co-integration of 2D and more conventional materials like Si will be required. In the 2nd part of the presentation we will focus on the introduction of MX2 materials in the 300 mm pilot line, focusing on the challenges and potential solutions.